描述 / Descriptions

TO-92 塑封封装 PNP 半导体三极管。Silicon PNP transistor in a TO-92 Plastic Package.

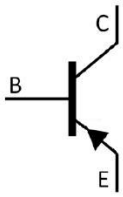
特征 / Features

高集电极直流电流和集电极耗散功率。
High P_C and I_C.

用途 / Applications

用于中功率放大。
Medium power amplifier applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1：Collector　　PIN 2：Base　　PIN 3：Emitter

放大及印章代码 / hFE Classifications & Marking

见印章说明。See Marking Instructions.

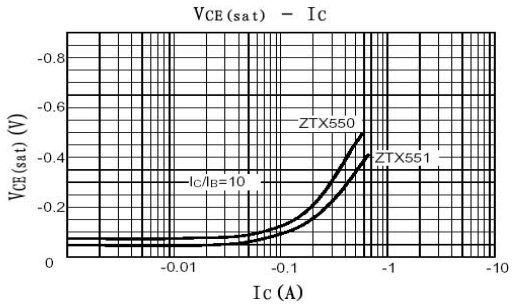
极限参数 / Absolute Maximum Ratings(Ta=25℃)

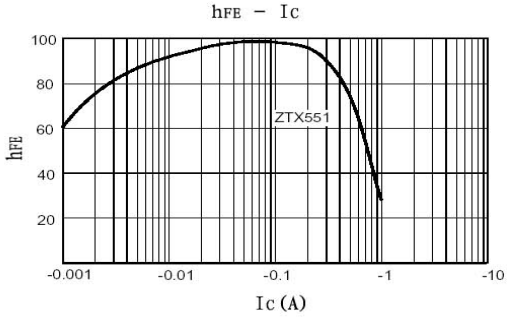
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-45	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-1.0	A
Peak Collector Current	I_{CM}	-2.0	A
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

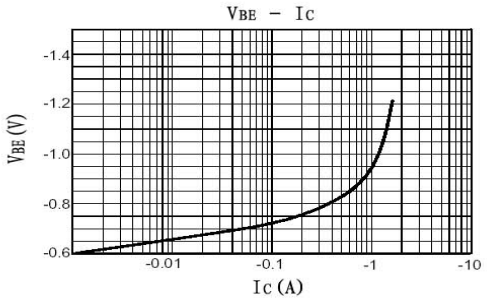
电性能参数 / Electrical Characteristics(Ta=25℃)

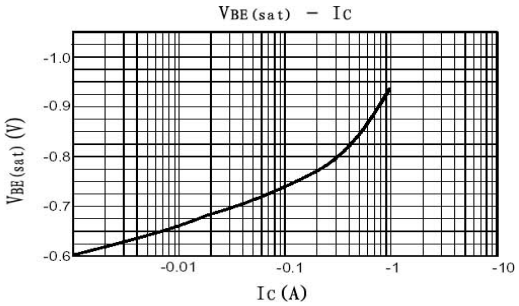
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=-100μA	-60			V
Collector to Emitter Breakdown Voltage	V_{CEO}	I_C=-10mA	-45			V
Emitter to Base Breakdown Voltage	V_{EBO}	I_E=-100μA	-5.0			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=-45V I_E=0			-0.1	μA
Emitter Cut-Off Current	I_{EBO}	V_{EB}=-4.0V I_C=0			-0.1	μA
DC Current Gain	$h_{FE(1)}$	I_C=-150mA V_{CE}=-10V	100		300	
	$h_{FE(2)}$	I_C=-1.0A V_{CE}=-10V	15			
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=-150mA I_B=-15mA			-0.25	V
Base -Emitter Saturation Voltage	$V_{BE(sat)}$	I_C=-150mA I_B=-15mA			-1.1	V
Transition Frequency	f_T	V_{CE}=-10V I_C=-50mA f=100MHz	150			MHz

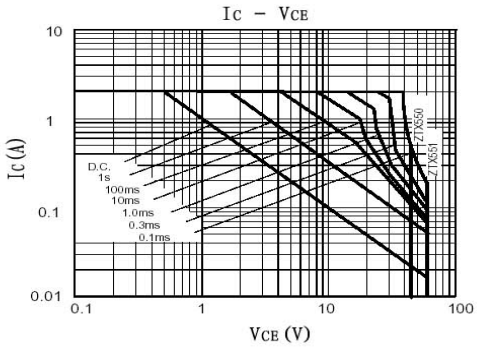
电参数曲线图 / Electrical Characteristic Curve





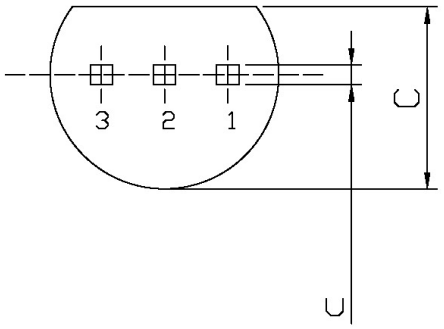


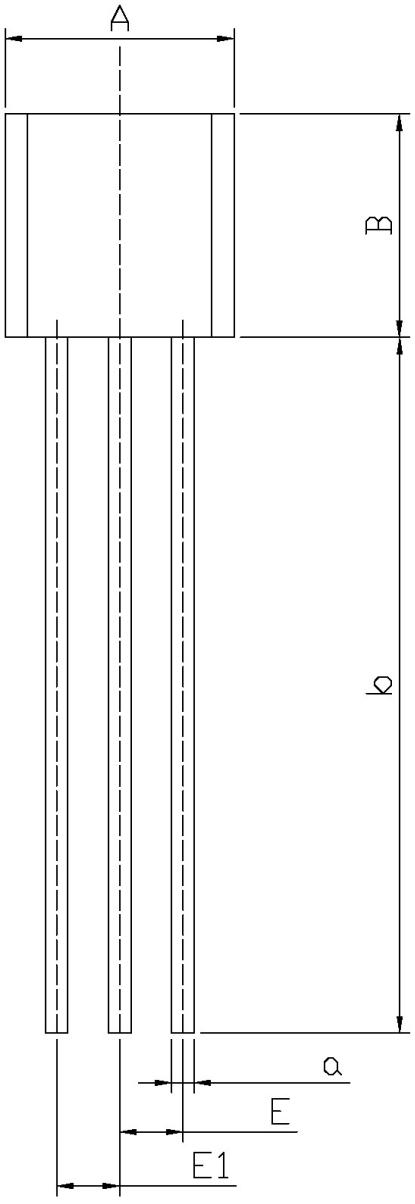




外形尺寸图 / Package Dimensions

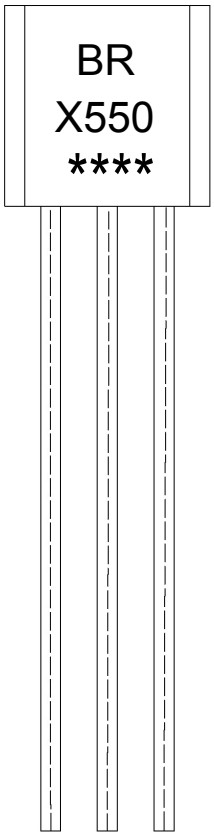
TO-92 Unit: mm





Symbol	Dimensions In Millmeters	
	Min	Max
A	4.4	4.8
B	4.3	4.7
b	13	15
a	0.40	0.60
E	1.22	1.32
E1	1.22	1.32
C	3.4	3.8
c	0.30	0.50

印章说明 / Marking Instructions



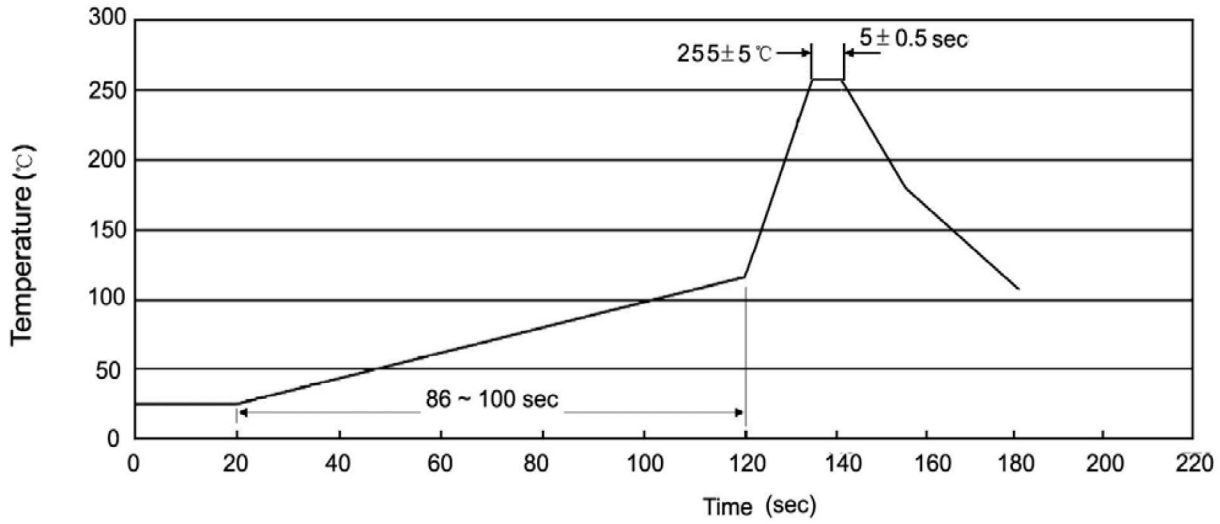
说明：

BR:	为公司代码
X550：	为型号代码
****：	为生产批号代码，随生产批号变化。

Note:

BR:	Company Code.
X550:	Product Type.
****:	Lot No. Code,code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

1、预热温度 25～150℃，时间 60～90sec;

2、峰值温度 255±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:25~150℃, Time:60~90sec.

2.Peak Temp.:255±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5℃　　时间：10±1 sec.　　Temp:270±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

编带包装 / AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92	3,000	1	120	10	30,000	328×230×42	小箱 480×346×235， 大箱 547×407×268

使用说明 / Notices